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PATENT
Docket No.: 020964-003900US

TOWNSEND and TOWNSEND and CREW LLP

By: Robert J. Jans

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

HAMZA YILMAZ et al.

Patent No.: 7,122,406

Issued: October 17, 2006

For: SEMICONDUCTOR DEVICE
PACKAGE DIEPAD HAVING
FEATURES FORMED BY
ELECTROPLATING

Confirmation No.: 7450

Examiner: Thien F. Tran

Art Unit: 2811

REQUEST FOR CERTIFICATE
OF CORRECTION UNDER 37
CFR 1.323

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 CFR § 1.323, Applicant submits a Certificate of Correction correcting drawings printed on the Letters Patent. The desired corrections are set forth on the form PTO/SB44, enclosed.

The Commissioner is hereby authorized to deduct the fee of \$100.00, pursuant to 37 CFR § 1.20(a), and any additional fees required or credit any overpayments to Deposit Account No. 20-1430.

Respectfully submitted,



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**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**Page 1 of 1

PATENT NO. : 7,122,406
APPLICATION NO.: 10/751,265
ISSUE DATE : October 17, 2006
INVENTOR(S) : Tat Keung Chan et al.

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the Drawings:

Replace Figure 7H, Sheet 12, with Figure 7H on the attached sheet of the formal drawings.

MAILING ADDRESS OF SENDER (Please do not use customer number below):

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